CLAIMS

1. A semiconductor device comprising

a first semiconductor comprising a substrate, and a semiconductor chip disposed on the major surface of said substrate and sealed with a resin;

a wiring board,

spacers disposed between said wiring board and said substrate and connecting said first semiconductor to said wiring board electrically; and

a second semiconductor electrically connected to said wiring board and disposed in the space formed by said wiring board, said substrate, and said spacer.

2. The semiconductor device according to claim 1, wherein a plurality of said semiconductors are disposed on said wiring board.

3. A method for manufacturing a semiconductor device comprising the steps of:

mounting a first semiconductor on the respective spacers of a spacer substrate formed by the sequence of a plurality of spacers for a semiconductor device;

mounting a second semiconductor on the opposite sides of the portions of said respective spacers whereon said first spacer has been connected, and in the same direction of said first semiconductor, respectively; and

splitting said spacer substrate for each of said semiconductor devices.